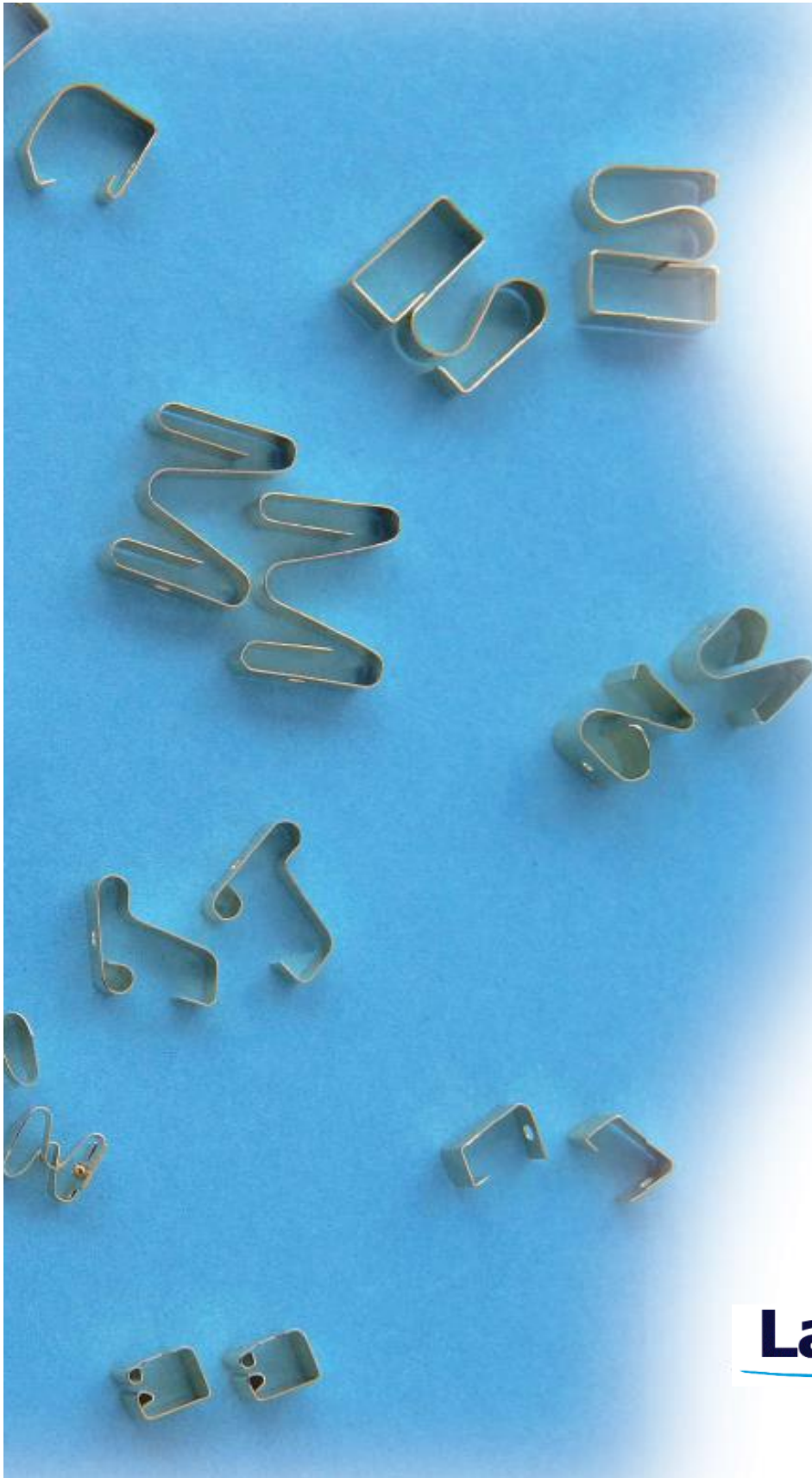
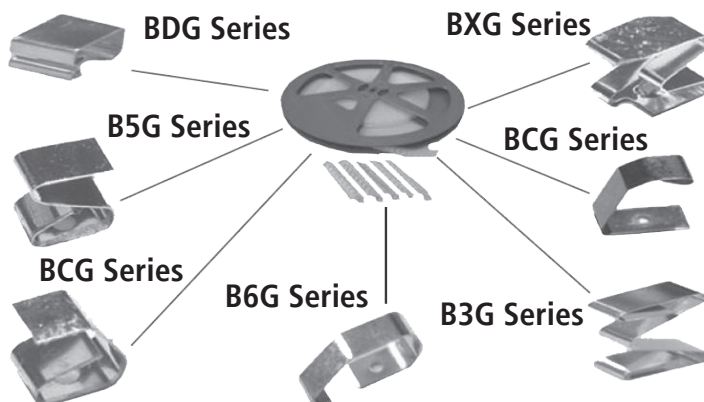




Laird™



SMD GROUNDING GASKETS

Laird Technologies develops and manufactures standard precision electronic SMD contacts for the use of grounding, carrying current and signals, and interconnect PCBs and devices.

Laird SMD contacts are available in a wide variety of plating options which allow for the maximum electrical current carrying performance and galvanic corrosion compatibility. The base material of Beryllium Copper features excellent resilience and electrical properties, thus making the contact suitable in electronic applications.

An array of designs in a standard format are ready for production.

FEATURES

- SMD contacts are RoHS compliant
- Simple board level EMC solutions for multiple grounding points.
- Low compression force
- Variety of shapes and sizes
- Available in other base material, e.g. Phosphor Bronze
- Standard surface Gold over Nickel, other options available (Tin, Nickel)
- Standard packaging, Tape and Reel

MARKETS

- Laptop computers, Tablets
- Networking equipment
- Printer
- Infotainment / Automotive
- Electronic Components
- Medical equipment and devices
- Digital cameras
- Mobile devices/Smart Phones/GPS

USA: +1.866.928.8181
Europe: +49.0.8031.2460.0
Asia: +86.755.2714.1166

EMI-DS-SMD-CONTACTS 1212

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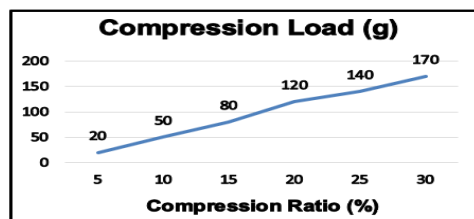
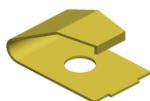
SMD Contacts overview

Part NO : 67BCG2003201508R00

Part Model:BCG-20X32X015

Size:2.0(W)X3.2(L)X1.5(H)

Material:BeCu Plating Ni/Au

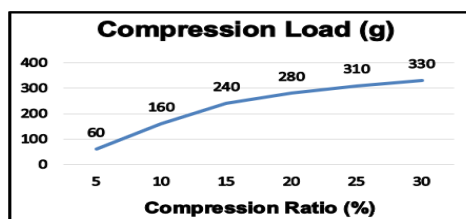


Part NO : 67TCG1502702010R0B

Part Model:TCG-15X27X020

Size:1.5(W)X2.7(L)X2.0(H)

Material:Ti Cu Plating Ni/Au

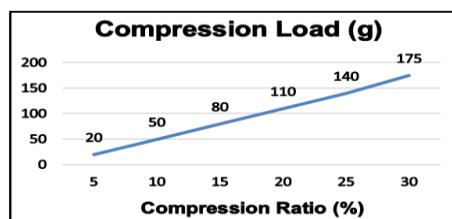


Part NO : 67BCG2004002008R00

Part Model:BCG-20X40X020

Size:2.0(W)X4.0(L)X2.0(H)

Material:BeCu Plating Ni/Au

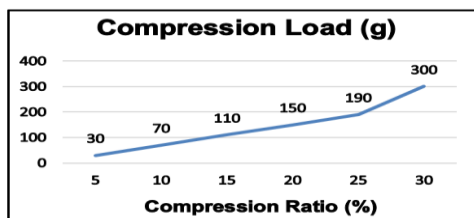
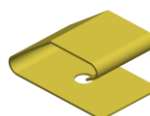


Part NO : 67BCG2504002108R00

Part Model:BCG-25X40X021

Size:2.5(W)X4.0(L)X2.1(H)

Material:BeCu Plating Ni/Au

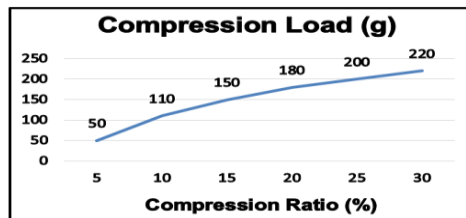


Part NO : 67BCG2003002508R00

Part Model:BCG-20X30X025

Size:2.0(W)X3.0(L)X2.5(H)

Material:BeCu Plating Ni/Au

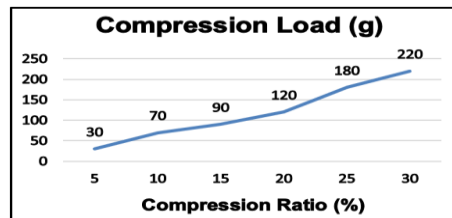
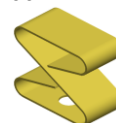


Part NO : 67B8G2004003710R00

Part Model:B8G-20X40X037

Size:2.0(W)X4.0(L)X3.7(H)

Material:BeCu Plating Ni/Au

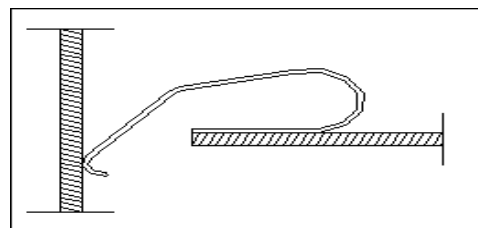


Part NO : 67B6G2007503015R00

Part Model:B6G-20X75X030

Size:2.0(W)X7.5(L)X3.0(H)

Material:BeCu Plating Ni/Au

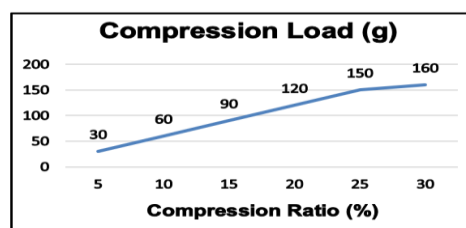


Part NO : 67B5G2003003108R0B

Part Model:B5G-20X30X031

Size:2.0(W)X3.0(L)X3.1(H)

Material:BeCu Plating Ni/Au

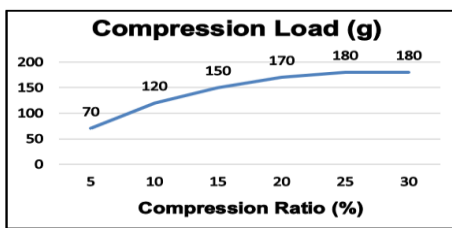


Part NO : 67BCG2003004010R00

Part Model:BCG-20X30X040

Size:2.0(W)X3.0(L)X4.0(H)

Material:BeCu Plating Ni/Au

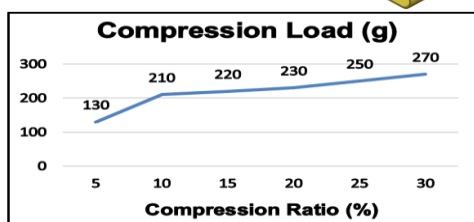


Part NO : 67BCG2503004010R00

Part Model:BCG-25X30X040

Size:2.5(W)X3.0(L)X4.0(H)

Material:BeCu Plating Ni/Au

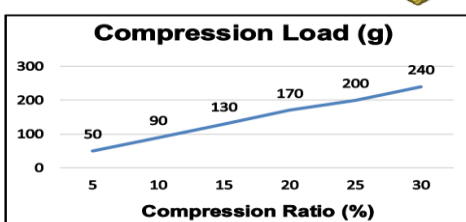
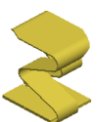


Part NO : 67BXG2503504008R00

Part Model:BXG-25X35X040

Size:2.5(W)X3.5(L)X4.0(H)

Material:BeCu Plating Ni/Au

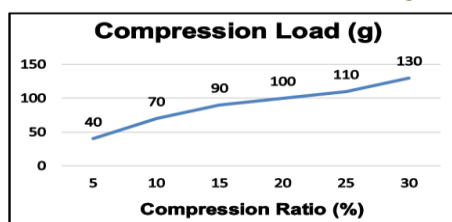
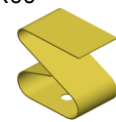


Part NO : 67B5G2504004108R00

Part Model:B5G-25X40X041

Size:2.5(W)X4.0(L)X4.1(H)

Material:BeCu Plating Ni/Au



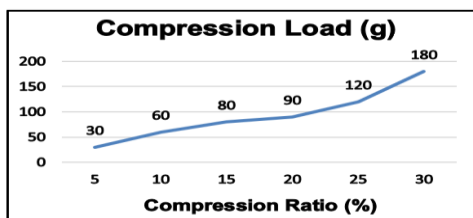
SMD Contacts overview

Part NO : 67BCG2504504810R00

Part Model:BCG-25X45X048

Size:2.5(W)X4.5(L)X4.8(H)

Material:BeCu Plating Ni/Au

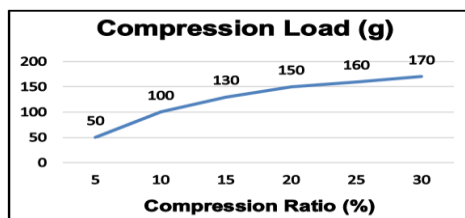


Part NO : 67BCG2504005010R00

Part Model:BCG-25X40X050

Size:2.5(W)X4.0(L)X5.0(H)

Material:BeCu Plating Ni/Au

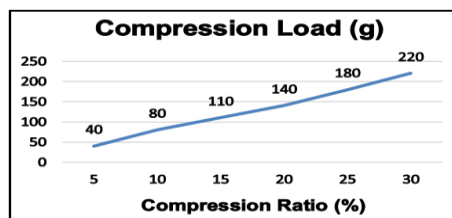
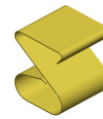


Part NO : 67B5G4004005108R0B

Part Model:B5G-40X40X051

Size:4.0(W)X4.0(L)X5.1(H)

Material:BeCu Plating Ni/Au

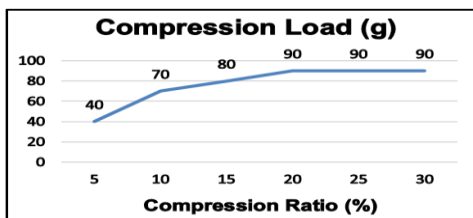


Part NO : 67BCG2004005310R00

Part Model:BCG-20X40X053

Size:2.0(W)X4.0(L)X5.3(H)

Material:BeCu Plating Ni/Au

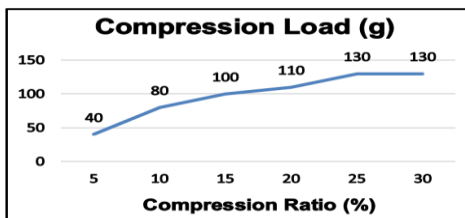


Part NO : 67BCG2504005510R00

Part Model:BCG-25X40X055

Size:2.5(W)X4.0(L)X5.5(H)

Material:BeCu Plating Ni/Au

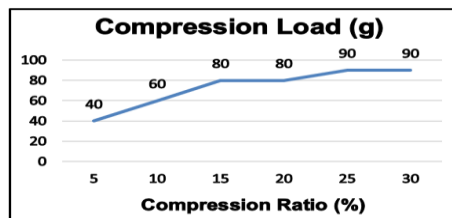


Part NO : 67BCG2004705710R00

Part Model:BCG-20X47X057

Size:2.0(W)X4.7(L)X5.7(H)

Material:BeCu Plating Ni/Au

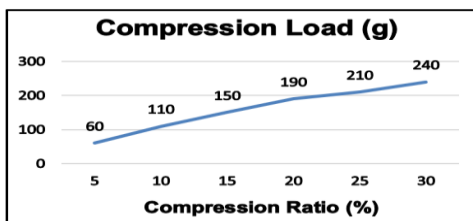


Part NO : 67B5G2504506010R00

Part Model:B5G-25X45X060

Size:2.5(W)X4.5(L)X6.0(H)

Material:BeCu Plating Ni/Au

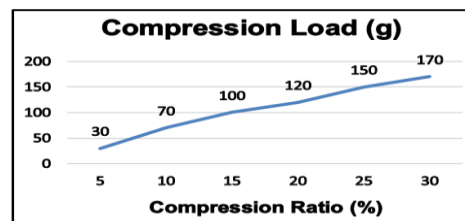


Part NO : 67B5G2007006215R00

Part Model:B5G-20X70X062

Size:2.0(W)X7.0(L)X6.2(H)

Material:BeCu Plating Ni/Au

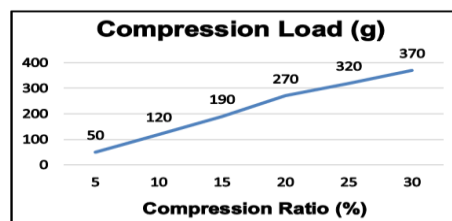


Part NO : 67BSG2004507012R0B

Part Model:BSG-20X45X070

Size:2.0(W)X4.5(L)X7.0(H)

Material:BeCu Plating Ni/Au

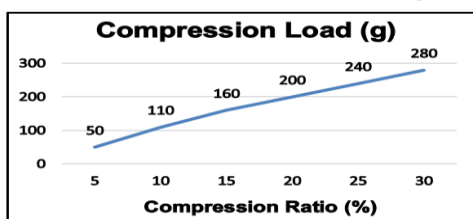
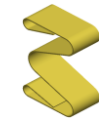


Part NO : 67B3G2504807010R0B

Part Model:B3G-25X48X070

Size:2.5(W)X4.8(L)X7.0(H)

Material:BeCu Plating Ni/Au

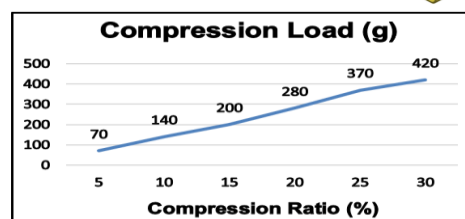


Part NO : 67BSG2506508015R00

Part Model:BSG-25X65X080

Size:2.5(W)X6.5(L)X8.0(H)

Material:BeCu Plating Ni/Au

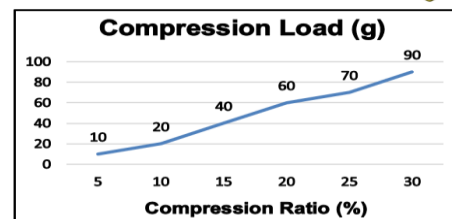


Part NO : 67B3G2507009010R0B

Part Model:B3G-25X70X090

Size:2.5(W)X7.0(L)X9.0(H)

Material:BeCu Plating Ni/Au



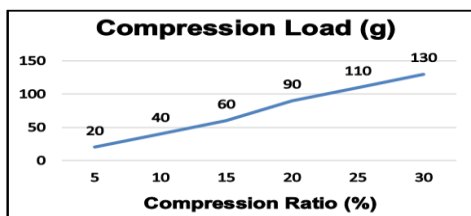
SMD Contacts overview

Part NO : 67B3G3006010010R0C

Part Model:B3G-30X60X100

Size:3.0(W)X6.0(L)X10(H)

Material:BeCu Plating Ni/Au

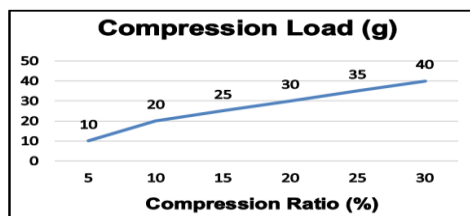


Part NO : 67BCG2006006010R00

Part Model:BCG-20X60X060

Size:2.0(W)X6.0(L)X6.0(H)

Material:BeCu Plating Ni/Au

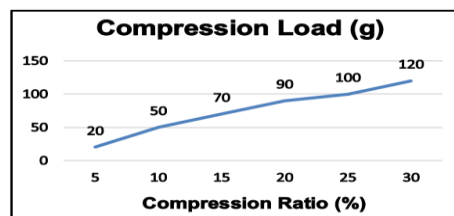
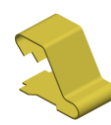


Part NO : 67BCG2504303510R00

Part Model:BCG-25X43X035

Size:2.5(W)X4.3(L)X3.5(H)

Material:BeCu Plating Ni/Au

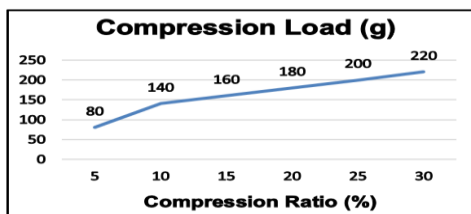


Part NO : 67B7G2504005010R00

Part Model:B7G- 25X40X050

Size:2.5(W)X4.0(L)X5.0(H)

Material:BeCu Plating Ni/Au

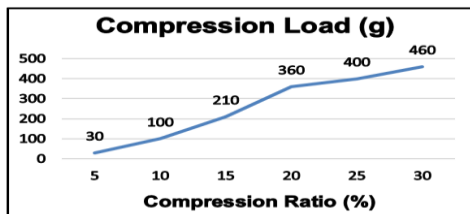


Part NO : 67BSG2507012015R0B

Part Model:BSG-25X70X120

Size:2.5(W)X7.0(L)X12(H)

Material:BeCu Plating Ni/Au

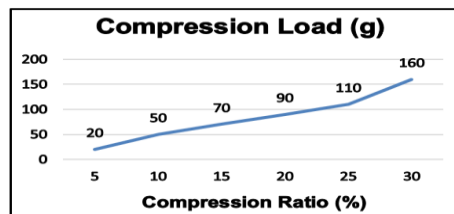
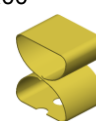


Part NO : 67B8G3004005108R00

Part Model:B8G-30X40X051

Size:3.0(W)X4.0(L)X5.1(H)

Material:BeCu Plating Ni/Au

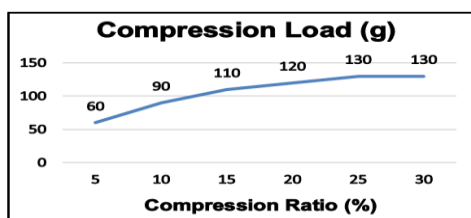


Part NO : 67BCG2504006010R00

Part Model:BCG-25X40X060

Size:2.5(W)X4.0(L)X6.0(H)

Material:BeCu Plating Ni/Au

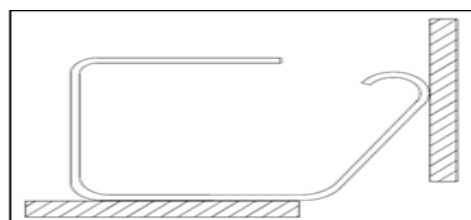


Part NO : 67BCG2006004015R00

Part Model:BCG- 20X60X040

Size:2.0(W)X6.0(L)X4.0(H)

Material:BeCu Plating Ni/Au

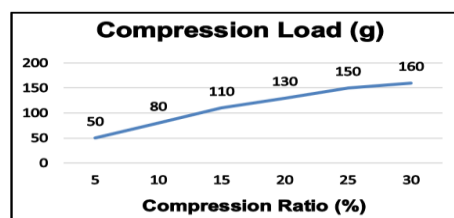


Part NO : 67B4G2504005410R00

Part Model:B4G- 25X40X054

Size:2.5(W)X4.0(L)X5.4(H)

Material:BeCu Plating Ni/Au

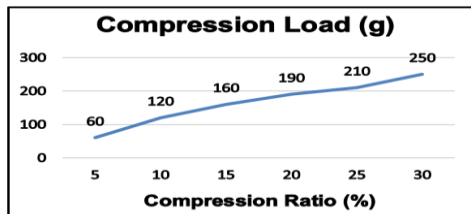


Part NO : 67B8G2004504510R00

Part Model:B8G-20X45X045

Size:2.0(W)X4.5(L)X4.5(H)

Material:BeCu Plating Ni/Au

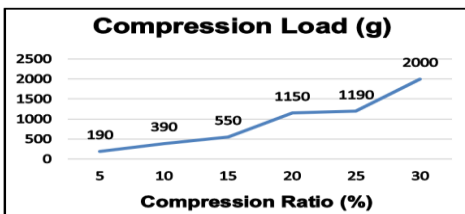


Part NO : 67BCG2005805015R00

Part Model:BCG-20X58X050

Size:2.0(W)X5.8(L)X5.0(H)

Material:BeCu Plating Ni/Au

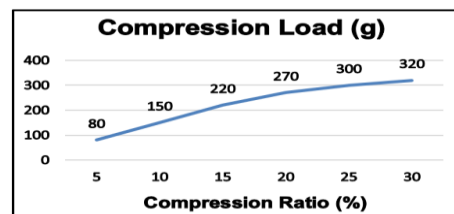


Part NO : 67TCG1502702010R0C

Part Model:TCG- 15X27X020(Z)

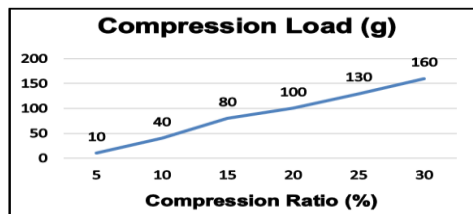
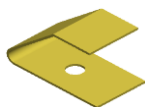
Size:1.5(W)X2.7(L)X2.0(H)

Material:Ti Cu Plating Ni/Au

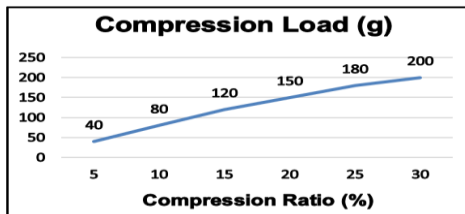


SMD Contacts overview

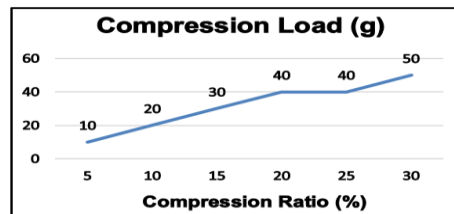
Part NO : 67BCG2003802008R00
Part Model:BCG-20X38X020
Size:2.0(W)X3.8(L)X2.0(H)
Material:BeCu Plating Ni/Au



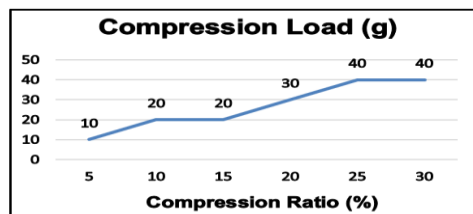
Part NO : 67B3G2504810010R00
Part Model:B3G-25X48X100
Size:2.5(W)X4.8(L)X10.0(H)
Material:BeCu Plating Ni/Au



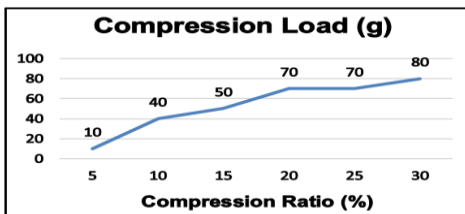
Part NO : 67BCG2003203508R00
Part Model:BCG-20X32X035
Size:2.0(W)X3.2(L)X3.5(H)
Material:BeCu Plating Ni/Au



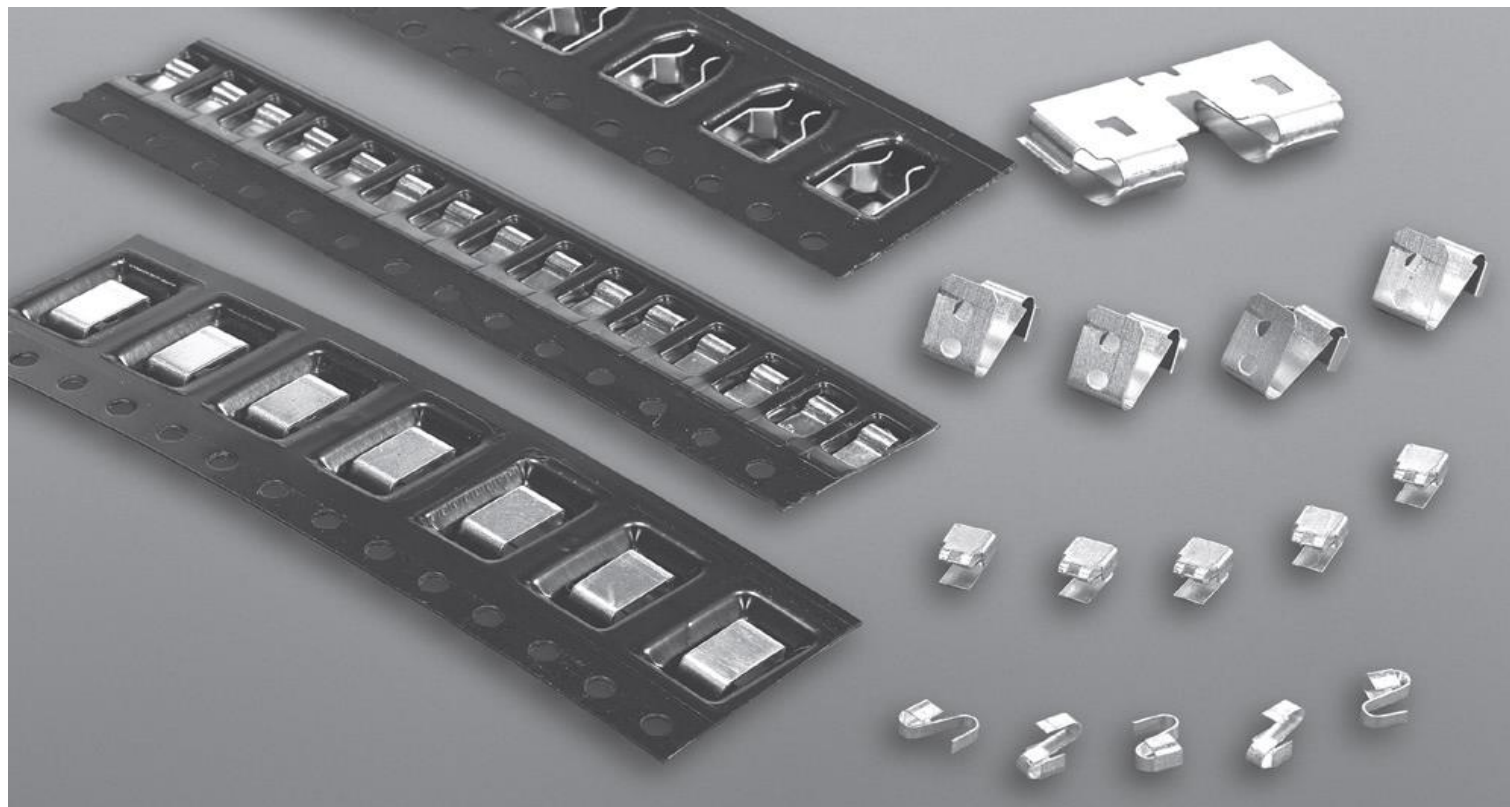
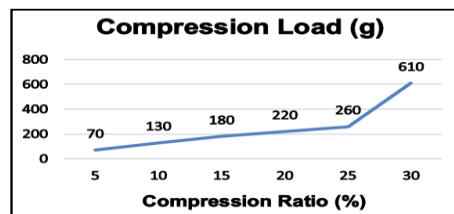
Part NO : 67BCG2004005508R00
Part Model:BCG-20X40X055
Size:2.0(W)X4.0(L)X5.5(H)
Material:BeCu Plating Ni/Au



Part NO : 67BCG2004504810R00
Part Model:BCG- 20X45X048
Size:2.0(W)X4.5(L)X4.8(H)
Material:BeCu Plating Ni/Au



Part NO : 67B8G2507006215R00
Part Model:B8G-25X70X062
Size:2.5(W)X7.0(L)X6.2(H)
Material:BeCu Plating Ni/Au



SMD Contacts specification

Part Model	Part Number	Width (mm)	Length (mm)	Height (mm)	Material	Plating Type	Stroke (mm)	Remark
B3G-20X35X048	67B3G2003504810R00	2.0	3.5	4.8	BeCu	Ni/Au	0.4~1.5	
B3G-20X38X055	67B3G2003805508R00	2.0	3.8	5.5	BeCu	Ni/Au	0.5~1.7	
B3G-25X48X070	67B3G2504807010R0B	2.5	4.8	7.0	BeCu	Ni/Au	0.5~2.5	
B3G-25X48X100	67B3G2504810010R00	2.5	4.8	10.0	BeCu	Ni/Au	0.8~3.5	
B3G-25X70X090	67B3G2507009010R0B	2.5	7.0	9.0	BeCu	Ni/Au	0.8~3.0	
B3G-30X60X100	67B3G3006010010R0C	3.0	6.0	10.0	BeCu	Ni/Au	0.8~3.5	
B3S-30X60X100	67B3S3006010010R00	3.0	6.0	10.0	BeCu	Ni/Tin	0.8~3.5	
B4G-25X40X054	67B4G2504005410R00	2.5	4.0	5.4	BeCu	Ni/Au	0.5~2.0	
B5G-20X30X031	67B5G2003003108R00	2.0	3.0	3.1	BeCu	Ni/Au	0.3~1.0	
B5G-20X70X062	67B5G2007006215R00	2.0	7.0	6.2	BeCu	Ni/Au	0.6~2.0	
B5G-25X40X041	67B5G2504004108R00	2.5	4.0	4.1	BeCu	Ni/Au	0.4~1.5	
B5G-25X45X060	67B5G2504506010R00	2.5	4.5	6.0	BeCu	Ni/Au	0.4~2.0	
B5S-25X40X041	67B5S2504004108R00	2.5	4.0	4.1	BeCu	Ni/Tin	0.4~1.5	
B5G-40X40X051	67B5G4004005108R0B	4.0	4.0	5.1	BeCu	Ni/Au	0.5~1.6	
B5S-40X40X051	67B5S4004005108R00	4.0	4.0	5.1	BeCu	Ni/Tin	0.5~1.6	
B6G-20X75X030	67B6G2007503015R00	2.0	7.5	3.0	BeCu	Ni/Au	0.4~1.8	Side Contact
B7G-25X40X050	67B7G2504005010R00	2.5	4.0	3.7	BeCu	Ni/Au	0.3~1.5	
B8G-20X40X037	67B8G2004003710R00	2.0	4.0	3.7	BeCu	Ni/Au	0.5~1.2	
B8G-20X45X045	67B8G2004504510R00	2.0	4.5	4.5	BeCu	Ni/Au	0.5~1.5	
B8G-25X70X062	67B8G2507006215R00	2.5	7.0	6.2	BeCu	Ni/Au	0.5~2.0	
B8G-25X70X090	67B8G2507009012R0B	2.5	7.0	9.0	BeCu	Ni/Au	0.8~3.0	
B8G-30X40X051	67B8G3004005108R00	3.0	4.0	5.1	BeCu	Ni/Au	0.5~1.6	
BCG-20X30X025	67BCG2003002508R00	2.0	3.0	2.5	BeCu	Ni/Au	0.2~0.8	
BCG-20X30X040	67BCG2003004010R00	2.0	3.0	4.0	BeCu	Ni/Au	0.4~1.5	
BCG-20X32X015	67BCG2003201508R00	2.0	3.2	1.5	BeCu	Ni/Au	0.1~0.6	
BCG-20X32X035	67BCG2003203508R00	2.0	3.2	3.5	BeCu	Ni/Au	0.5~1.5	
BCG-20X38X020	67BCG2003802008R00	2.0	3.8	2.0	BeCu	Ni/Au	0.3~0.8	

BCG-20X40X020	67BCG2004002008R00	2.0	4.0	2.0	BeCu	Ni/Au	0.3~0.6	
BCG-20X40X053	67BCG2004005310R00	2.0	4.0	5.3	BeCu	Ni/Au	0.3~2.0	
BCG-20X40X055	67BCG2004005508R00	2.0	4.0	5.5	BeCu	Ni/Au	0.5~2.5	
BCG-20X45X048	67BCG2004504810R00	2.0	4.5	4.8	BeCu	Ni/Au	0.5~1.5	
BCG-20X47X057	67BCG2004705710R00	2.0	4.7	5.7	BeCu	Ni/Au	0.6~2.2	
BCG-20X58X050	67BCG2005805015R00	2.0	5.8	5.0	BeCu	Ni/Au	0.5~1.5	
BCG-20X60X040	67BCG2006004015R00	2.0	6.0	4.0	BeCu	Ni/Au	0.4~1.4	Side Contact
BCG-20X60X060	67BCG2006006010R00	2.0	6.0	6.0	BeCu	Ni/Au	0.5~2.0	
BCG-25X30X040	67BCG2503004010R00	2.5	3.0	4.0	BeCu	Ni/Au	0.3~1.2	
BCG-25X40X021	67BCG2504002108R00	2.5	4.0	2.1	BeCu	Ni/Au	0.2~0.6	
BCG-25X40X050	67BCG2504005010R00	2.5	4.0	5.0	BeCu	Ni/Au	0.3~1.5	
BCG-25X40X055	67BCG2504005510R00	2.5	4.0	5.5	BeCu	Ni/Au	0.3~2.0	
BCG-25X40X060	67BCG2504006010R00	2.5	4.0	6.0	BeCu	Ni/Au	0.5~2.0	
BCG-25X43X035	67BCG2504303510R00	2.5	4.3	3.5	BeCu	Ni/Au	0.3~1.0	
BCG-25X45X048	67BCG2504504810R00	2.5	4.5	4.8	BeCu	Ni/Au	0.5~1.5	
BDG-20X35X027	67BDG2003502715R00	2.0	3.5	2.7	BeCu	Ni/Au	NA	Wires fixed
BDG-25X34X027	67BDG2503402710R00	2.0	3.4	2.7	BeCu	Ni/Au	NA	Wires fixed
BSG-20X45X070	67BSG2004507012R0B	2.0	4.5	7.0	BeCu	Ni/Au	0.5~2.1	
BSG-25X65X080	67BSG2506508015R0B	2.5	6.5	8.0	BeCu	Ni/Au	0.5~2.4	
BSG-25X70X120	67BSG2507012015R00	2.5	7.0	12.0	BeCu	Ni/Au	0.6~3.5	
BSG-25X70X120(Z)	67BSG2507012015R0A	2.5	7.0	12.0	BeCu	Ni/Au	0.6~3.5	
BSS-25X70X120(Z)	67BSS2507012015R00	2.5	7.0	12.0	BeCu	Ni/Tin	0.6~3.5	
BXG-25X35X040	67BXG2503504008R00	2.5	3.5	4.0	BeCu	Ni/Au	0.3~1.4	
P3G-20X36X026	67P3G2003602610R00	2.0	3.6	2.6	Phosphor bronze	Ni/Au	0.2~0.8	
PCG-20X32X015	67PCG2003201508R00	2.0	3.2	1.5	Phosphor bronze	Ni/Au	0.1~0.5	
TCG-15X27X020	67TCG1502702010R0B	1.5	2.7	2.0	Ti Cu	Ni/Au	0.2~0.6	
TCG-15X27X020(Z)	67TCG1502702010R0C	1.5	2.7	2.0	Ti Cu	Ni/Au	0.2~0.6	
BCG-12X23X015	67BCG1202301508R00	1.2	2.3	1.5	BeCu	Ni/Au	0.1~0.5	
P5S-20X30X031	67P5S2003003108R00	2.0	3.0	3.1	Phosphor bronze	Ni/Tin	0.3~1.0	

SMD Contacts Character

Features:

- 1.Copper Beryllium is a high strength and high conductivity alloy.
- 2.The thermal and electrical conductivities of beryllium copper promote it used in fields required heat dissipation and current carrying capacity.
- 3.Copper Beryllium, high strength alloys, has less density than conventional special coppers.
- 4.Copper beryllium alloys are available in variety of product forms.

Physical Properties

Item	
Density -g/cm ³	8.36
Thermal Expansion Coefficient (20°C~200°C)-m/m/°C	9.7 x 10-6
Thermal Conductivity-cal/(cm.s.°C)	0.25
Melting Temperature-°C	870~980

Mechanical and Electrical Properties

Item	Before Treatment	After Treatment
Heat treatment		2hr 315°C
Tensile Strength-Kgf	67~70	141~152
Yielding Strength-Kgf	—	127~138
Elongation Percentage-%	21	3
Hardness-HV	176~216	300~410
Conductivity Percentage-IACS*	22~28	Good in Au plated





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